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Kind regards,

Team Nexperia

# 74HC237-Q100

3-to-8 line decoder, demultiplexer with address latches

Rev. 1 — 14 January 2013

Product data sheet

## 1. General description

The 74HC237-Q100 is a 3-to-8 line decoder, demultiplexer with latches at the three address inputs ( $A_n$ ). The 74HC237-Q100 essentially combines the 3-to-8 decoder function with a 3-bit storage latch. When the latch is enabled ( $\overline{LE} = \text{LOW}$ ), the 74HC237-Q100 acts as a 3-to-8 active LOW decoder. When the latch enable ( $\overline{LE}$ ) goes from LOW-to-HIGH, the last data present at the inputs before this transition, is stored in the latches. Further address changes are ignored as long as  $\overline{LE}$  remains HIGH. The output enable input ( $\overline{E1}$  and  $E2$ ) controls the state of the outputs independent of the address inputs or latch operation. All outputs are HIGH unless  $\overline{E1}$  is LOW and  $E2$  is HIGH. The 74HC237-Q100 is ideally suited for implementing non-overlapping decoders in 3-state systems and strobed (stored address) applications in bus-oriented systems.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Combines 3-to-8 decoder with 3-bit latch
- Multiple input enable for easy expansion or independent controls
- Active HIGH mutually exclusive outputs
- Low-power dissipation
- Complies with JEDEC standard no. 7A
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V ( $C = 200\text{ pF}$ ,  $R = 0\text{ }\Omega$ )

## 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC237D-Q100	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1



### 4. Functional diagram

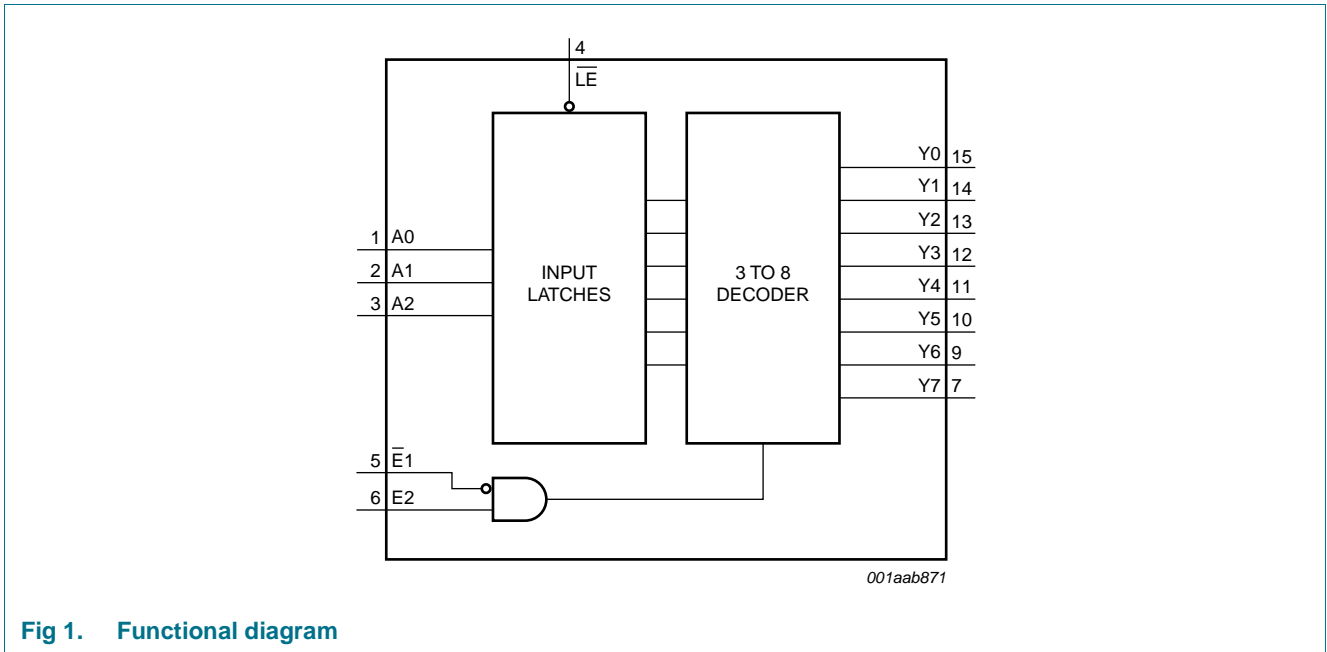


Fig 1. Functional diagram

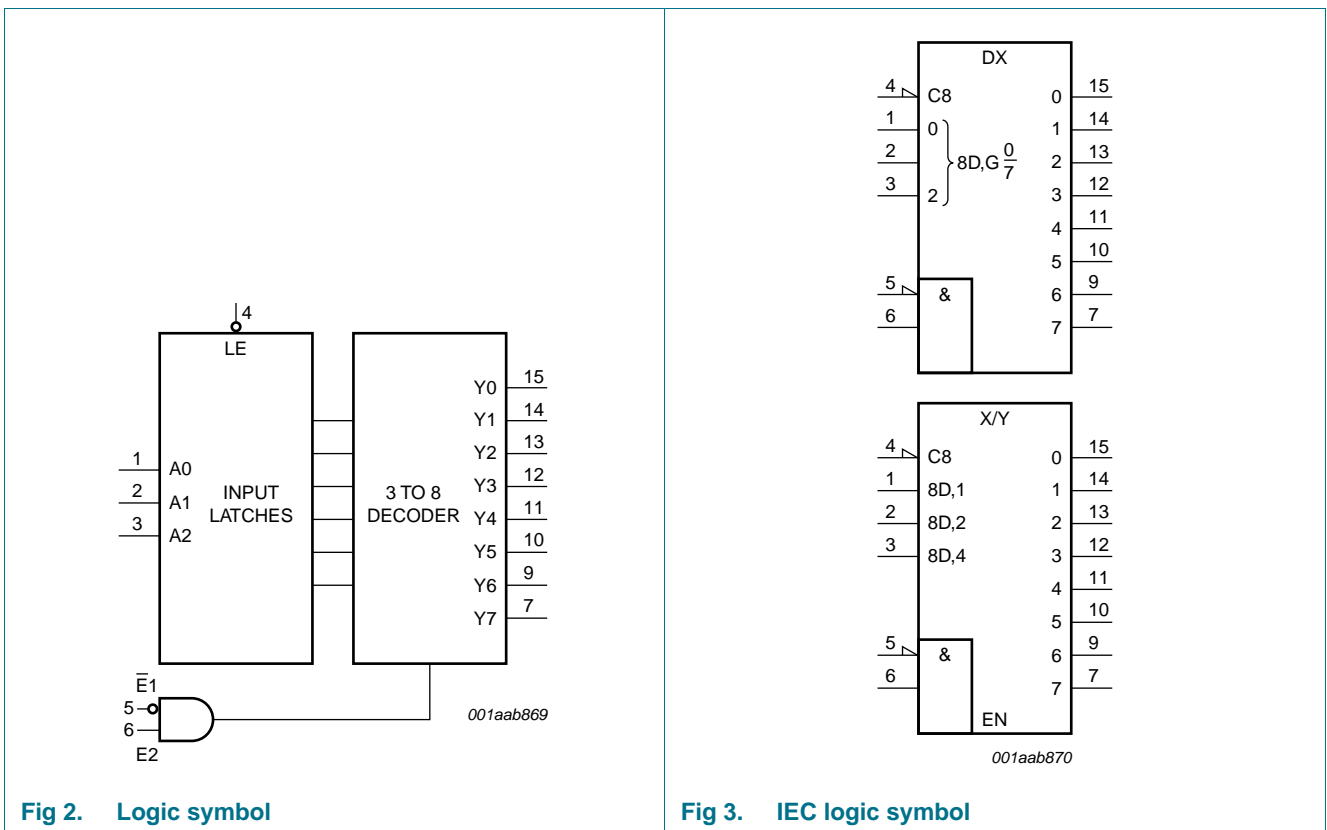


Fig 2. Logic symbol

Fig 3. IEC logic symbol

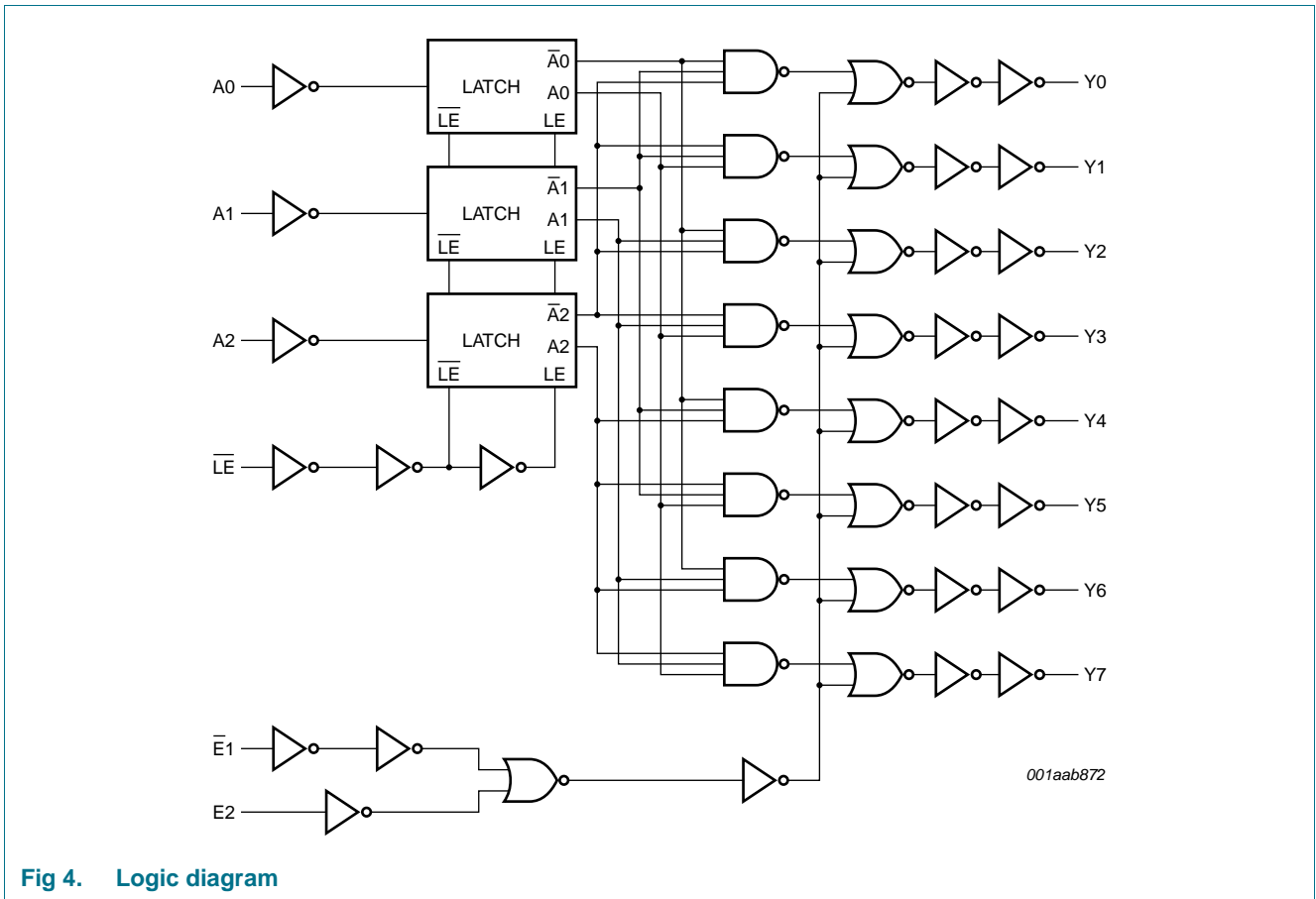


Fig 4. Logic diagram

## 5. Pinning information

### 5.1 Pinning

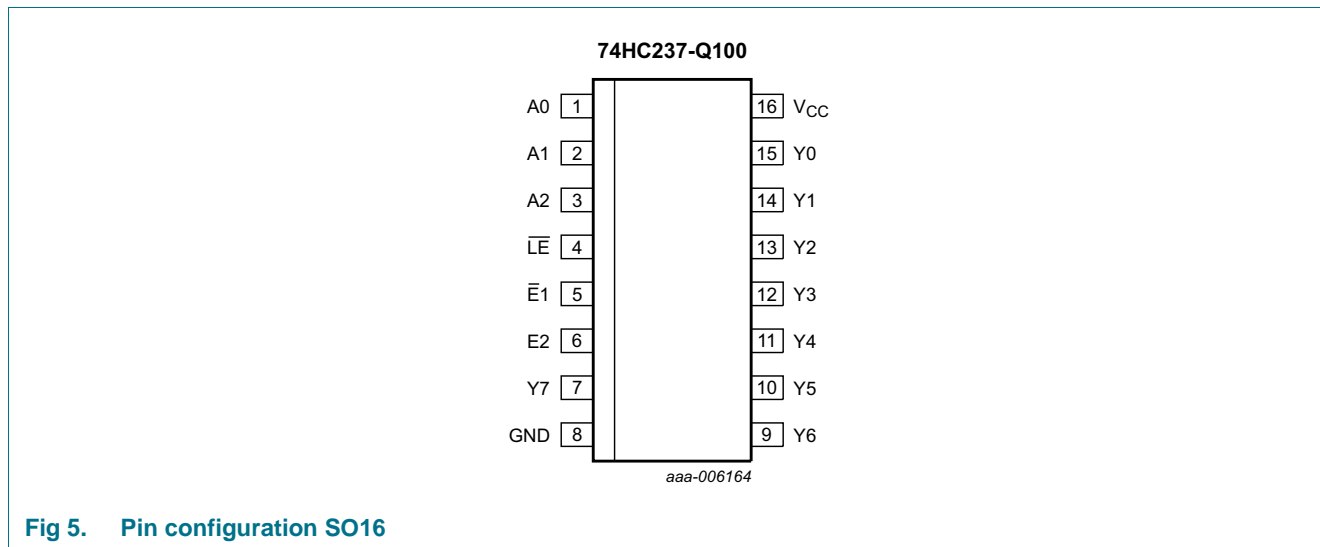


Fig 5. Pin configuration SO16

### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
A0 to A2	1, 2, 3	data input
$\overline{LE}$	4	latch enable input (active LOW)
$\overline{E1}$	5	data enable input 1 (active LOW)
E2	6	data enable input 2 (active HIGH)
Y0 to Y7	15, 14, 13, 12, 11, 10, 9, 7	output
GND	8	ground (0 V)
V <sub>CC</sub>	16	supply voltage

## 6. Functional description

Table 3. Function table

Enable			Input			Output							
$\overline{LE}$	$\overline{E1}$	E2	A0	A1	A2	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
H	L	H	X	X	X	stable							
X	H	X	X	X	X	L	L	L	L	L	L	L	L
X	X	L	X	X	X	L	L	L	L	L	L	L	L
L	L	H	L	L	L	H	L	L	L	L	L	L	L
L	L	H	H	L	L	L	H	L	L	L	L	L	L
L	L	H	L	H	L	L	L	H	L	L	L	L	L
L	L	H	H	H	L	L	L	L	H	L	L	L	L
L	L	H	L	L	H	L	L	L	L	H	L	L	L
L	L	H	H	L	H	L	L	L	L	L	H	L	L
L	L	H	L	H	H	L	L	L	L	L	L	H	L
L	L	H	H	H	H	L	L	L	L	L	L	L	H

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7	V
$I_{IK}$	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$	-	$\pm 20$	mA
$I_{OK}$	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$	-	$\pm 20$	mA
$I_O$	output current	$V_O = -0.5\text{ V}$ to $(V_{CC} + 0.5\text{ V})$	-	$\pm 25$	mA
$I_{CC}$	supply current		-	+50	mA
$I_{GND}$	ground current		-	-50	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation		[1]	500	mW

[1] For SO16 package:  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.

## 8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		2.0	5.0	6.0	V
$V_I$	input voltage		0	-	$V_{CC}$	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	°C

**Table 5. Recommended operating conditions ...continued**  
 Voltages are referenced to GND (ground = 0 V) ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.0\text{ V}$	-	-	625	ns/V
		$V_{CC} = 4.5\text{ V}$	-	1.67	139	ns/V
		$V_{CC} = 6.0\text{ V}$	-	-	83	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**  
 At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	$T_{amb} = 25\text{ }^\circ\text{C}$			$T_{amb} = -40\text{ }^\circ\text{C to } +85\text{ }^\circ\text{C}$		$T_{amb} = -40\text{ }^\circ\text{C to } +125\text{ }^\circ\text{C}$		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 2.0\text{ V}$	1.5	1.2	-	1.5	-	1.5	-	V
		$V_{CC} = 4.5\text{ V}$	3.15	2.4	-	3.15	-	3.15	-	V
		$V_{CC} = 6.0\text{ V}$	4.2	3.2	-	4.2	-	4.2	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 2.0\text{ V}$	-	0.8	0.5	-	0.5	-	0.5	V
		$V_{CC} = 4.5\text{ V}$	-	2.1	1.35	-	1.35	-	1.35	V
		$V_{CC} = 6.0\text{ V}$	-	2.8	1.8	-	1.8	-	1.8	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$								
		$I_O = -20\text{ }\mu\text{A}; V_{CC} = 2.0\text{ V}$	1.9	2.0	-	1.9	-	1.9	-	V
		$I_O = -20\text{ }\mu\text{A}; V_{CC} = 4.5\text{ V}$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -20\text{ }\mu\text{A}; V_{CC} = 6.0\text{ V}$	5.9	6.0	-	5.9	-	5.9	-	V
		$I_O = -4.0\text{ mA}; V_{CC} = 4.5\text{ V}$	3.98	4.32	-	3.84	-	3.7	-	V
	$I_O = -5.2\text{ mA}; V_{CC} = 6.0\text{ V}$	5.48	5.81	-	5.34	-	5.2	-	V	
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$								
		$I_O = 20\text{ }\mu\text{A}; V_{CC} = 2.0\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 20\text{ }\mu\text{A}; V_{CC} = 4.5\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 20\text{ }\mu\text{A}; V_{CC} = 6.0\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 4.0\text{ mA}; V_{CC} = 4.5\text{ V}$	-	0.15	0.26	-	0.33	-	0.4	V
	$I_O = 5.2\text{ mA}; V_{CC} = 6.0\text{ V}$	-	0.16	0.26	-	0.33	-	0.4	V	
$I_I$	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 6.0\text{ V}$	-	-	$\pm 0.1$	-	$\pm 1.0$	-	$\pm 1.0$	$\mu\text{A}$
$I_{CC}$	supply current	$V_I = V_{CC}$ or GND; $I_O = 0\text{ A};$ $V_{CC} = 6.0\text{ V}$	-	-	8.0	-	80	-	160	$\mu\text{A}$
$C_I$	input capacitance		-	3.5	-	-	-	-	-	pF

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V);  $C_L = 50$  pF unless otherwise specified; for test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	$T_{amb} = 25\text{ °C}$			$T_{amb} = -40\text{ °C}$ to $+85\text{ °C}$		$T_{amb} = -40\text{ °C}$ to $+125\text{ °C}$		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$t_{pd}$	propagation delay	An to $Y_n$ ; see <a href="#">Figure 6</a> <sup>[1]</sup>								
		$V_{CC} = 2.0\text{ V}$	-	52	160	-	200	-	240	ns
		$V_{CC} = 4.5\text{ V}$	-	19	32	-	40	-	48	ns
		$V_{CC} = 5\text{ V}$ ; $C_L = 15\text{ pF}$	-	16	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	15	27	-	34	-	41	ns
		$\overline{LE}$ to $Y_n$ ; see <a href="#">Figure 6</a> <sup>[1]</sup>								
		$V_{CC} = 2.0\text{ V}$	-	61	190	-	240	-	285	ns
		$V_{CC} = 4.5\text{ V}$	-	22	38	-	48	-	57	ns
		$V_{CC} = 5\text{ V}$ ; $C_L = 15\text{ pF}$	-	19	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	18	32	-	41	-	48	ns
		$\overline{E}1$ to $Y_n$ ; see <a href="#">Figure 7</a> <sup>[1]</sup>								
		$V_{CC} = 2.0\text{ V}$	-	47	145	-	180	-	220	ns
		$V_{CC} = 4.5\text{ V}$	-	17	29	-	36	-	44	ns
		$V_{CC} = 5\text{ V}$ ; $C_L = 15\text{ pF}$	-	14	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	14	25	-	31	-	38	ns
		$t_t$	transition time	$E2$ to $Y_n$ ; see <a href="#">Figure 6</a> <sup>[1]</sup>						
$V_{CC} = 2.0\text{ V}$	-			47	145	-	180	-	220	ns
$V_{CC} = 4.5\text{ V}$	-			17	29	-	36	-	44	ns
$V_{CC} = 5\text{ V}$ ; $C_L = 15\text{ pF}$	-			14	-	-	-	-	-	ns
$V_{CC} = 6.0\text{ V}$	-			14	25	-	31	-	38	ns
$Y_n$ ; see <a href="#">Figure 6</a> and <a href="#">Figure 7</a> <sup>[2]</sup>										
$V_{CC} = 2.0\text{ V}$	-			19	75	-	95	-	110	ns
$V_{CC} = 4.5\text{ V}$	-			7	15	-	19	-	22	ns
$t_W$	pulse width	$\overline{LE}$ HIGH; see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0\text{ V}$	50	11	-	65	-	75	-	ns
		$V_{CC} = 4.5\text{ V}$	10	4	-	13	-	15	-	ns
		$V_{CC} = 6.0\text{ V}$	9	3	-	11	-	13	-	ns
$t_{su}$	set-up time	An to $\overline{LE}$ ; see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0\text{ V}$	50	6	-	65	-	75	-	ns
		$V_{CC} = 4.5\text{ V}$	10	2	-	13	-	15	-	ns
		$V_{CC} = 6.0\text{ V}$	9	2	-	11	-	13	-	ns



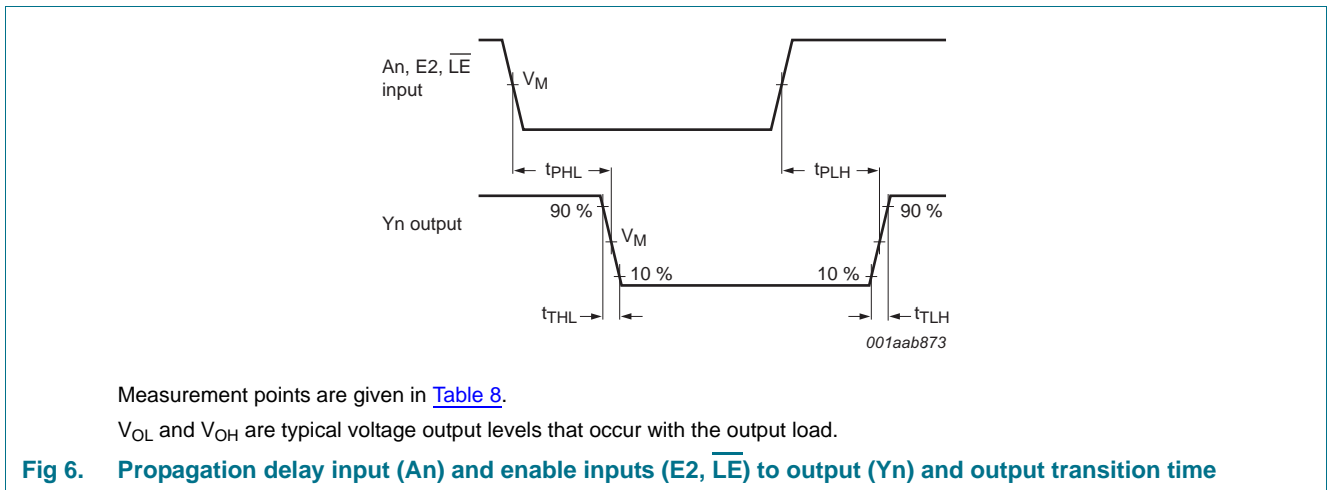
**Table 7. Dynamic characteristics ...continued**

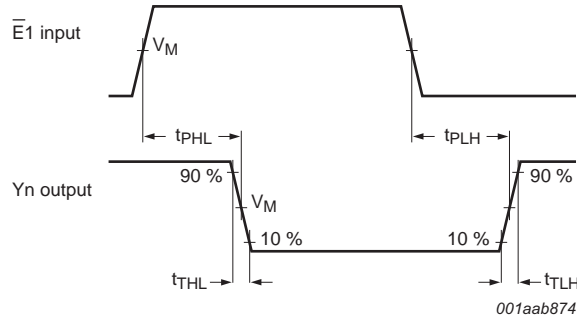
*Voltages are referenced to GND (ground = 0 V);  $C_L = 50$  pF unless otherwise specified; for test circuit see [Figure 9](#).*

Symbol	Parameter	Conditions	$T_{amb} = 25\text{ }^{\circ}\text{C}$			$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$		$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$t_h$	hold time	An to $\overline{LE}$ ; see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0\text{ V}$	30	3	-	40	-	45	-	ns
		$V_{CC} = 4.5\text{ V}$	6	1	-	8	-	9	-	ns
		$V_{CC} = 6.0\text{ V}$	5	1	-	7	-	8	-	ns
$C_{PD}$	power dissipation capacitance	$C_L = 50\text{ pF}$ ; $f = 1\text{ MHz}$ ; $V_I = \text{GND to } V_{CC}$	[9]	-	60	-	-	-	-	pF

- [1]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .
- [2]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .
- [3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o)$  where:  
 $f_i$  = input frequency in MHz;  
 $f_o$  = output frequency in MHz;  
 $C_L$  = output load capacitance in pF;  
 $V_{CC}$  = supply voltage in V;  
 $N$  = number of inputs switching;  
 $\sum(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

## 11. Waveforms

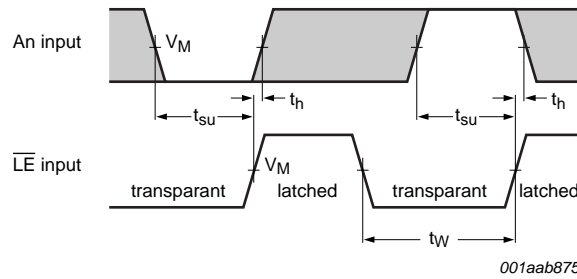




Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 7. Propagation enable inputs ( $\bar{E}1$ ) to output ( $Yn$ ) and output transition time**



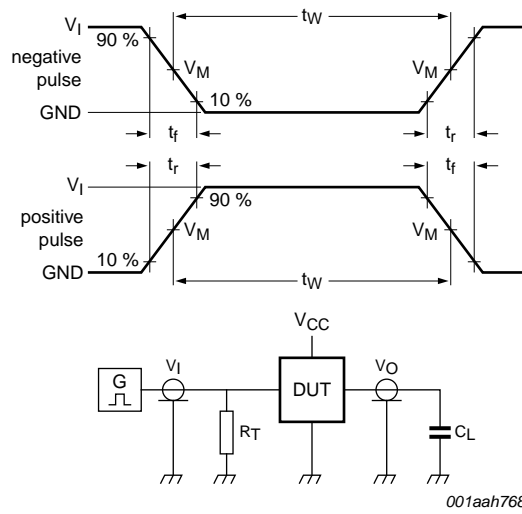
Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 8. The data input ( $A_n$ ) to latch enable input ( $\bar{LE}$ ) set-up times, latch enable input ( $\bar{LE}$ ) to data input ( $A_n$ ) hold times and latch enable input ( $\bar{LE}$ ) pulse width**

**Table 8. Measurement points**

Type	Input	Output
	$V_M$	$V_M$
74HC237-Q100	$0.5V_{CC}$	$0.5V_{CC}$



001aah768

Test data is given in [Table 9](#).

Definitions test circuit:

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_L$  = Load resistance.

S1 = Test selection switch.

**Fig 9. Test circuit for measuring switching times**

**Table 9. Test data**

Type	Input		Load	Test
	$V_I$	$t_r, t_f$	$C_L$	
74HC237-Q100	$V_{CC}$	6.0 ns	15 pF, 50 pF	$t_{PLH}, t_{PHL}$

## 12. Application information

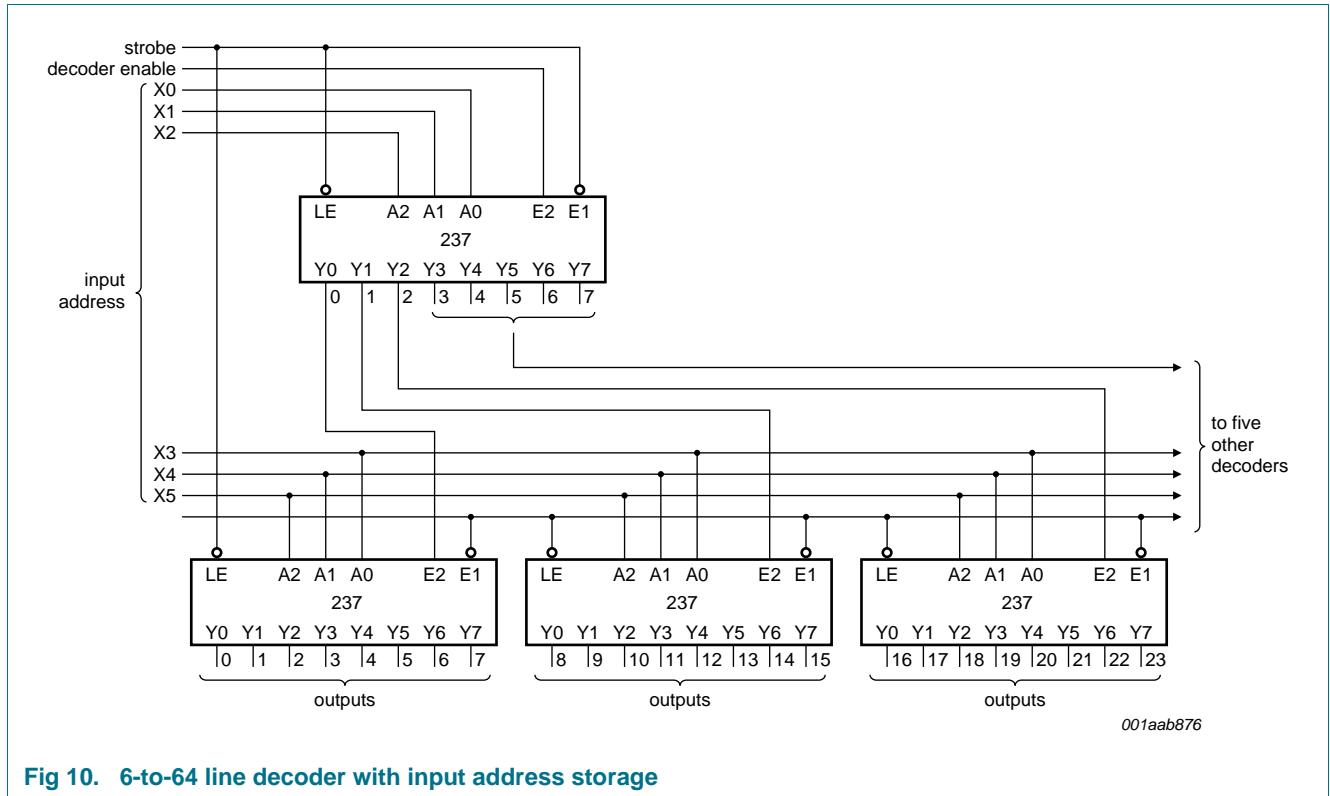


Fig 10. 6-to-64 line decoder with input address storage

13. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

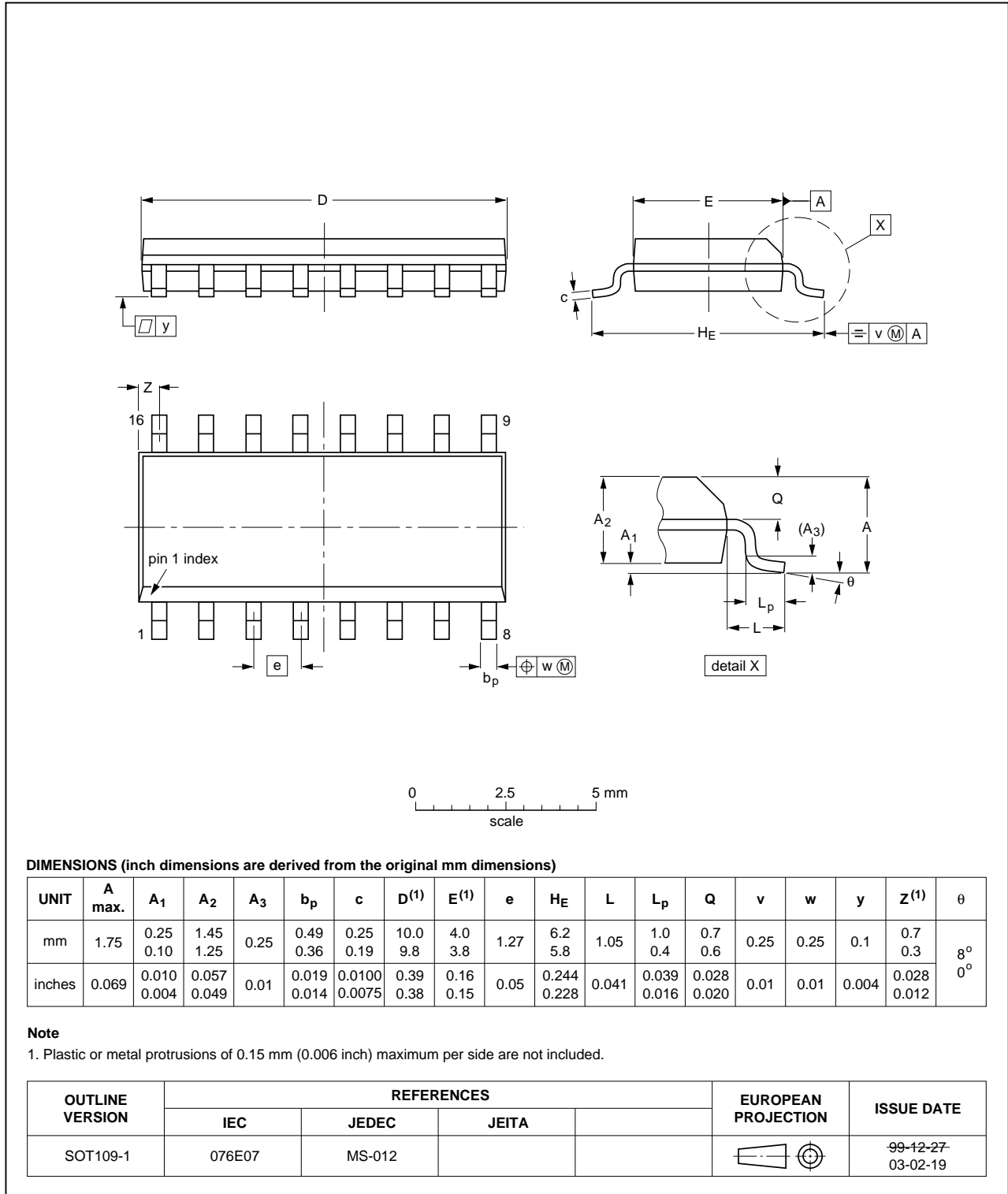


Fig 11. Package outline SOT109-1 (SO16)

## 14. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
MIL	Military
TTL	Transistor-Transistor Logic

## 15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC237_Q100 v.1	20130114	Product data sheet	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Date of release: 14 January 2013

Document identifier: 74HC237\_Q100